



COPPER & FIBER CABLES ... *Get Connected, RIGHT on Time!*

# OVER-MOLD CAPABILITIES

**CABLCON** offers gentle over-molding and encapsulation of electronic components. Our molding process is an innovative manufacturing process between injection molding and potting. It is a cost effective method of protecting electronic components. When used for cable and connector molding, it offers superior strain relief compared to conventional injection molding.

**Benefits:**

- Complete sealing of the components providing water-tight encapsulation
- Temperature and solvent resistant
- Effective strain relief
- Allows gentle pre-molding of connectors
- Components and wires are not damaged or dislocated in cavities
- Easy to encapsulate fragile components

**Applications:**

- Mold connectors with strain relief
- Seal multi-wire connectors
- Mold strain relief and grommets
- Seal micro-switches
- Over-mold various electronic shapes



Strong adhesion and bonding characteristics with a wide variety of substrates, including; ABS, PA 6, 6, PBT, PC, PE (crosslinked), PEI, PES, PUR and PVC.



**Technical Data:**

**Mechanical & Physical**

**Standard or Test Method**

**Class Alpha**

**Class Beta**

Color		Black	Black
Cold Flexibility	oC	-40oC	-40oC
Flammability Rating	UL 94	UL 94-V0	UL 94-V0
Glass Transition Temperature	oC	-36oC	-35oC
Injection Temperature	oC	200-240oC	200-240oC
Working Temperature	oC	-40 to 125oC	-40 to 125oC
Softening Point	oC	175oC +/- 5oC	175oC +/- 5oC
Thermal Expansion Coefficient		5E -04	5E -04
Density or Specific Gravity	DIN 53479, S S.G.	0.98	0.98
Elongation at Rupture	ASTM D 638-00 %	400	800
Shore-A-Hardness	ASTM D 2240-85	90	92
Shore-D-Hardness	ASTM D 2240-85	56	59
Tensile Strength at Rupture	N/mm2	4.5	11
Viscosity @ 210oC	ASTM D 3236-88 mPas	3700	7000

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